

CERAMIC MICROELECTROMECHANICAL STRUCTURE

Abstract of the Disclosure

A microelectromechanical structure and method is disclosed. A ceramic substrate preferably is formed from low temperature co-fired ceramic sheets. A low 5 loss photodefinable dielectric planarizing layer is formed over one surface of the ceramic substrate. This layer can be a sacrificial layer or a subsequent sacrificial layer added. A photodefined conductor is printed over the low loss dielectric planarizing layer 10 and formed with the sacrificial layer into a structural circuit component. In one aspect of the invention, a switch is formed with a biasing actuator and deflectable member formed over the biasing actuator and moveable into open and closed circuit positions.